



LSOP4, DC Input, Photo Transistor Coupler

Description

The BF101X series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic LSOP4 package.

With the robust coplanar double mold structure, BF101X series provide the most stable isolation feature.

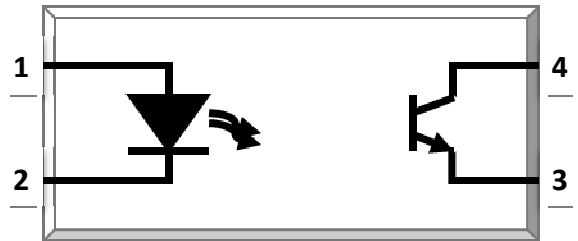
Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- RoHS & REACH Compliance
- MSL class 1
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1, GB8898

Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

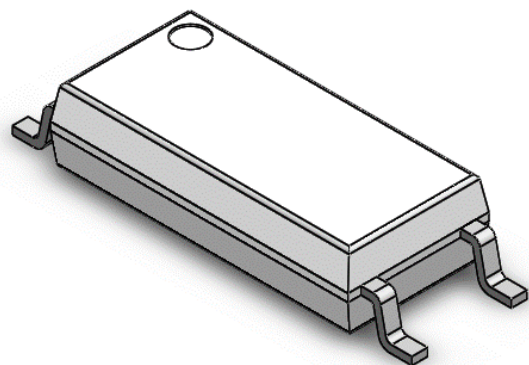
SCHEMATIC



PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

PACKAGE OUTLINE





LSOP4, DC Input, Photo Transistor Coupler

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	80	V	
Emitter - Collector Voltage	V_{ECO}	7	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	P_{tot}	250	mW	
Isolation Voltage	V_{iso}	5000	V _{rms}	2
Operating Temperature	T_{opr}	-55~110	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	

Note 1. 100µs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%



LSOP4, DC Input, Photo Transistor Coupler

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C								
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE	
INPUT								
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA		
Reverse Current	I _R	-	-	10	μA	V _R =6V		
Input Capacitance	C _{in}	-	30	250	pF	V=0, f=1kHz		
OUTPUT								
Collector Dark Current	I _{CEO}	-	-	100	nA	V _{CE} =20V, I _F =0		
Collector-Emitter Breakdown Voltage	BV _{CEO}	80	-	-	V	I _C =0.1mA, I _F =0		
Emitter-Collector Breakdown Voltage	BV _{ECO}	7	-	-	V	I _E =0.1mA, I _F =0		
TRANSFER CHARACTERISTICS								
Current Transfer Ratio	BF1010	CTR	300	-	600	%	I _F =5mA, V _{CE} =5V	
	BF1015		50	-	150			
	BF1016		100	-	300			
	BF1017		80	-	160			
	BF1018		130	-	260			
	BF1019		200	-	400			
	BF1011		60	-	300		I _F =10mA, V _{CE} =5V	
	BF1012		63	-	125			
	BF1013		100	-	200			
	BF1014		160	-	320		I _F =1mA, V _{CE} =5V	
	BF1012		22	-	-			
	BF1013		34	-	-			
	BF1014		56	-	-			
Collector-Emitter Saturation Voltage	V _{CE(sat)}	-	0.1	0.3	V	I _F =10mA, I _C =1mA		
Isolation Resistance	R _{ISO}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.		
Floating Capacitance	C _{IO}	-	0.4	1	pF	V=0, f=1MHz		
Cut-off Frequency	F _c	-	80	-	kHz	V _{CE} =2V, I _C =2mA R _L =100Ω, -3dB	3	
Response Time (Rise)	Tr	-	5	18	μs	V _{CE} =2V, I _C =2mA R _L =100Ω	4	
Response Time (Fall)	Tf	-	6	18	μs		4	

Note 3. Fig.12&13

Note 4. Fig.14



CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

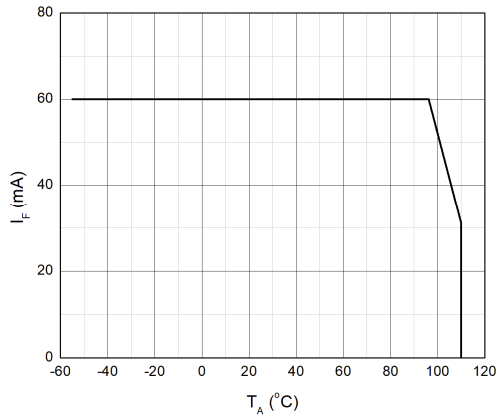


Fig.2 Collector Power Dissipation vs. Ambient Temperature

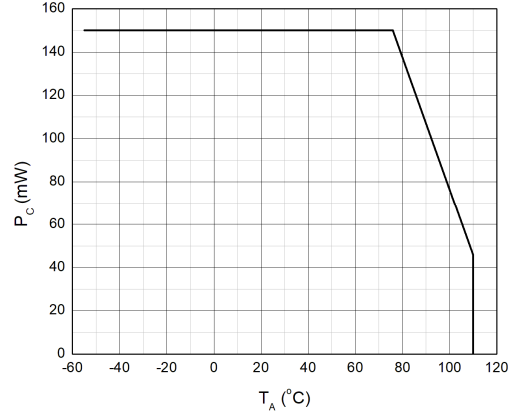


Fig.3 Forward Current vs. Forward Voltage

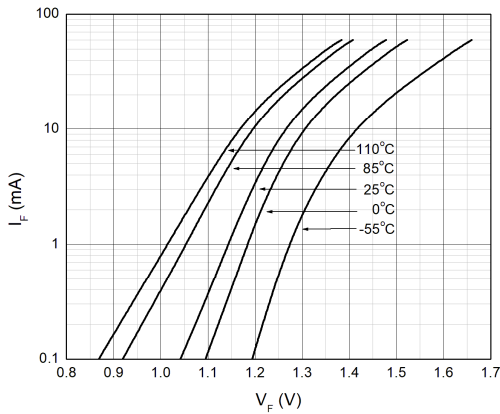


Fig.4 Collector Dark Current vs. Ambient Temperature

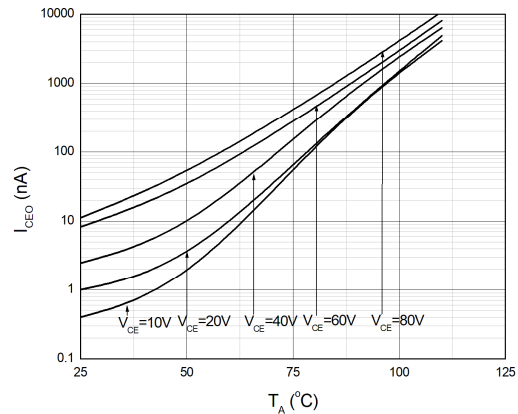


Fig.5 Collector Current vs. Collector-emitter Voltage

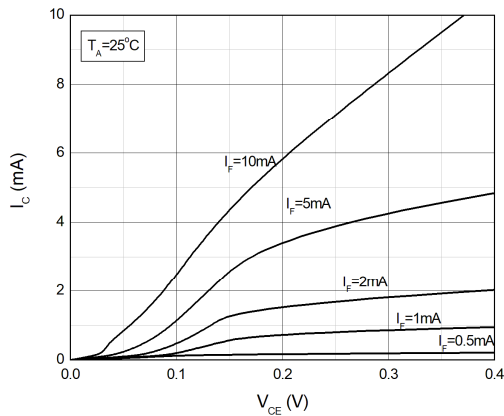
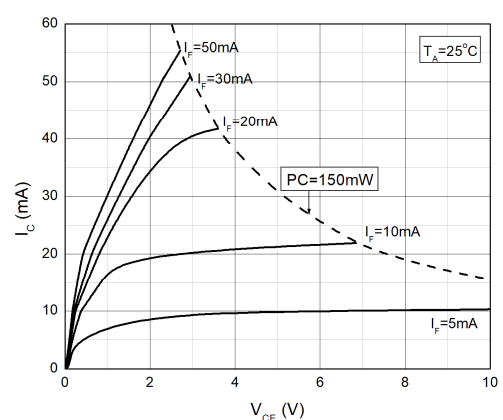


Fig.6 Collector Current vs. Collector-emitter Voltage





CHARACTERISTIC CURVES

Fig.7 Normalized Current Transfer Ratio vs. Forward Current

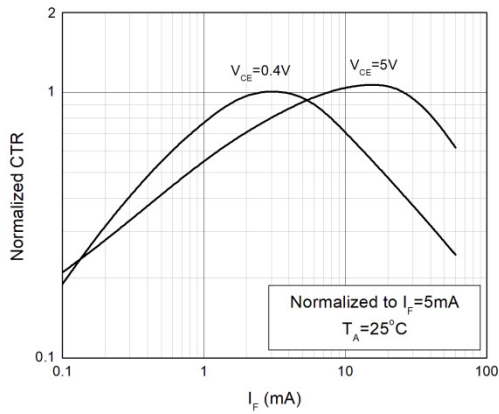


Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature

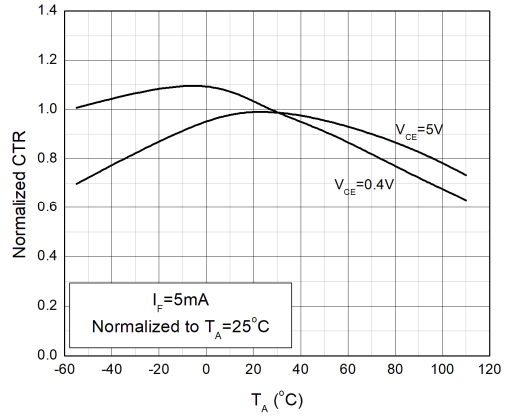


Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature

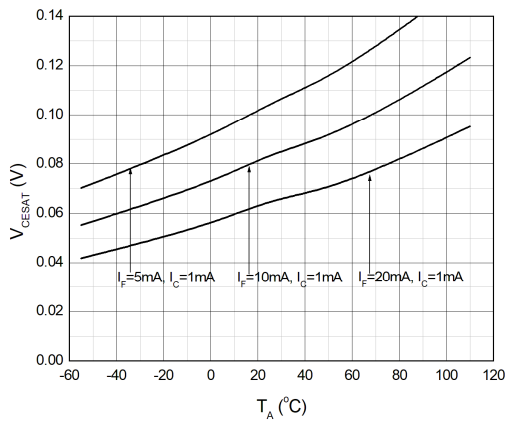


Fig.10 Switching Time vs. Load Resistance

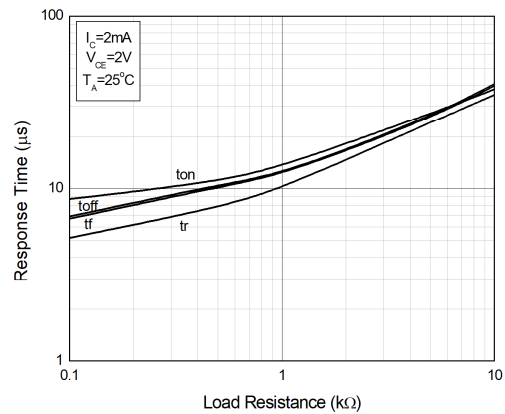
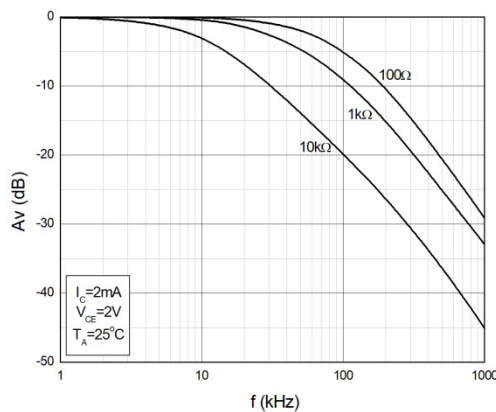


Fig.11 Frequency Response





TEST CIRCUITS

Fig.12 Test Circuits of Response Time

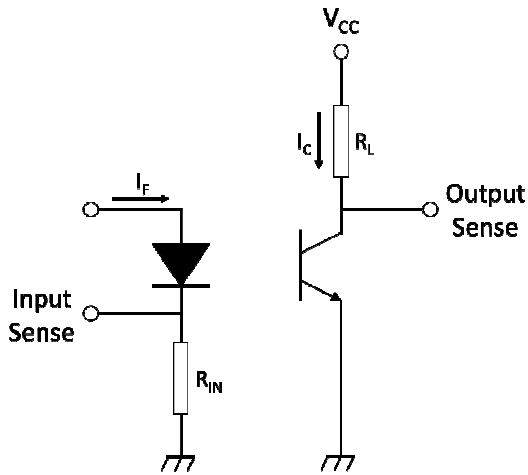


Fig.13 Curves of Response Time

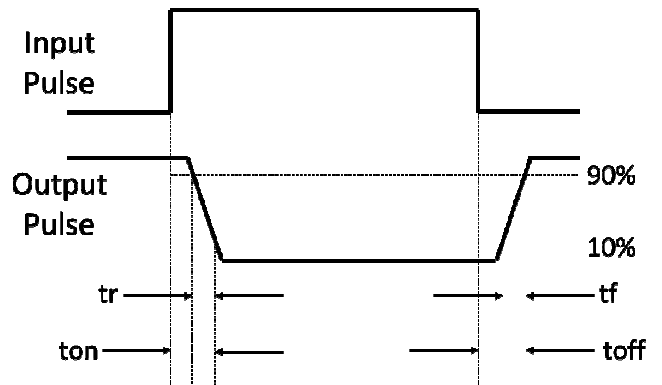
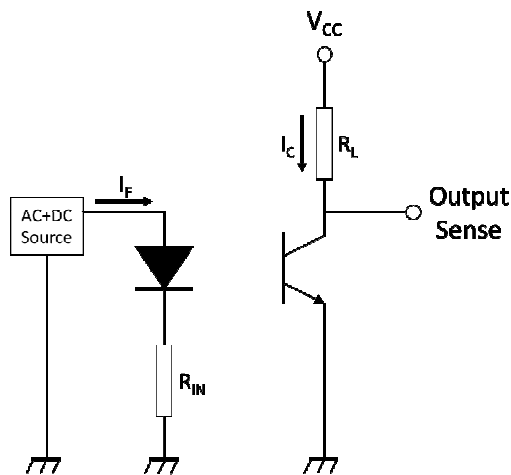
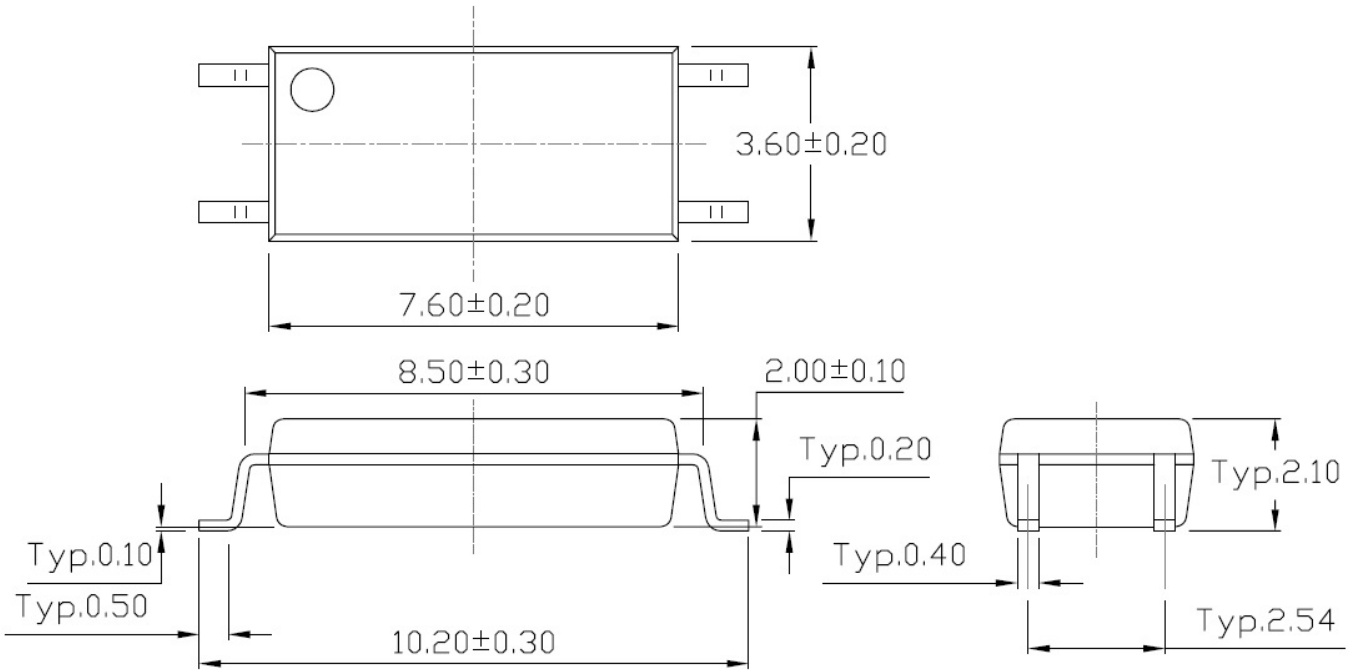


Fig.14 Test Circuits of Frequency Response

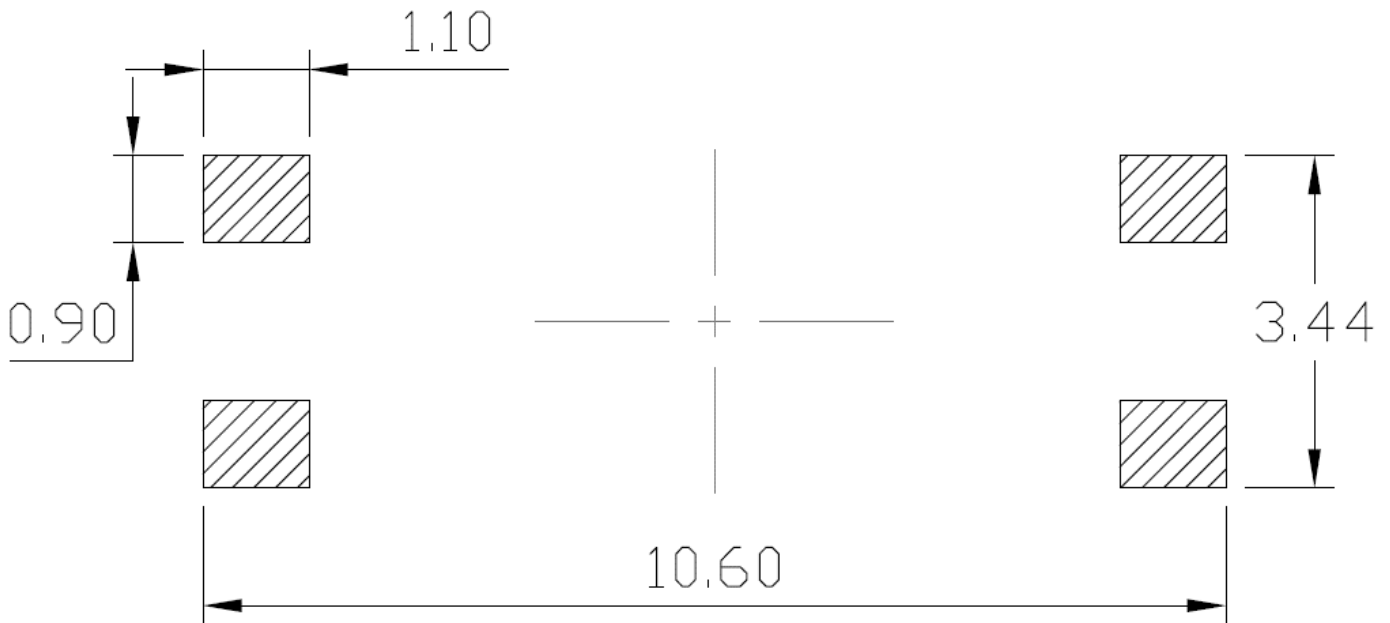




PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)



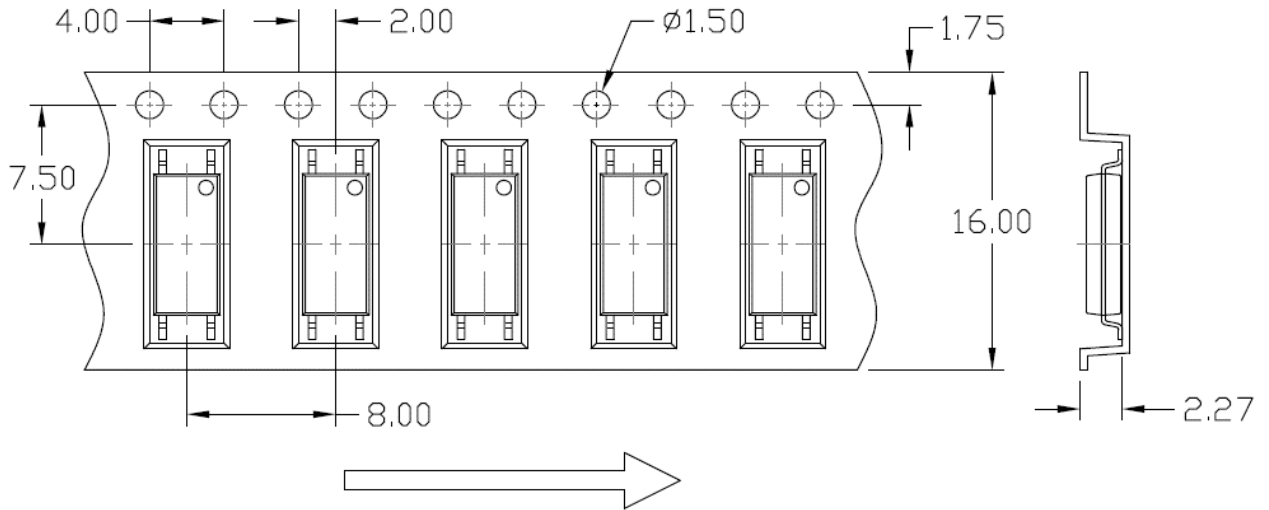
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



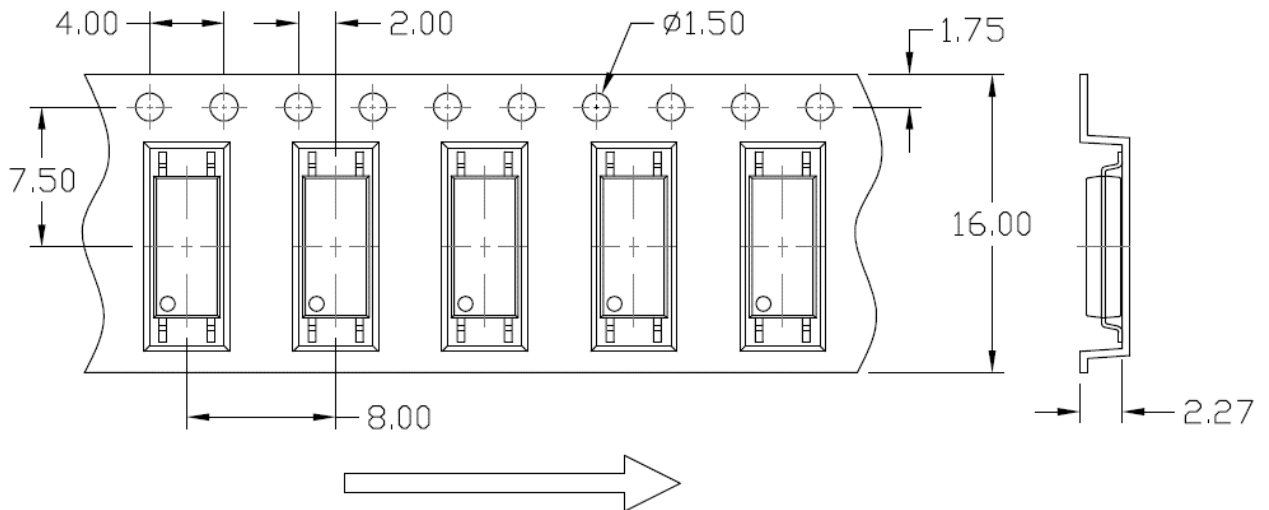


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



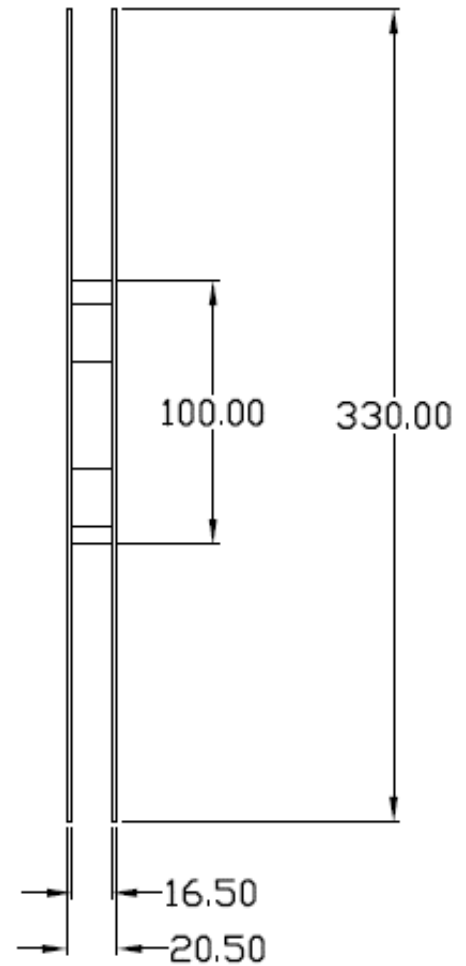
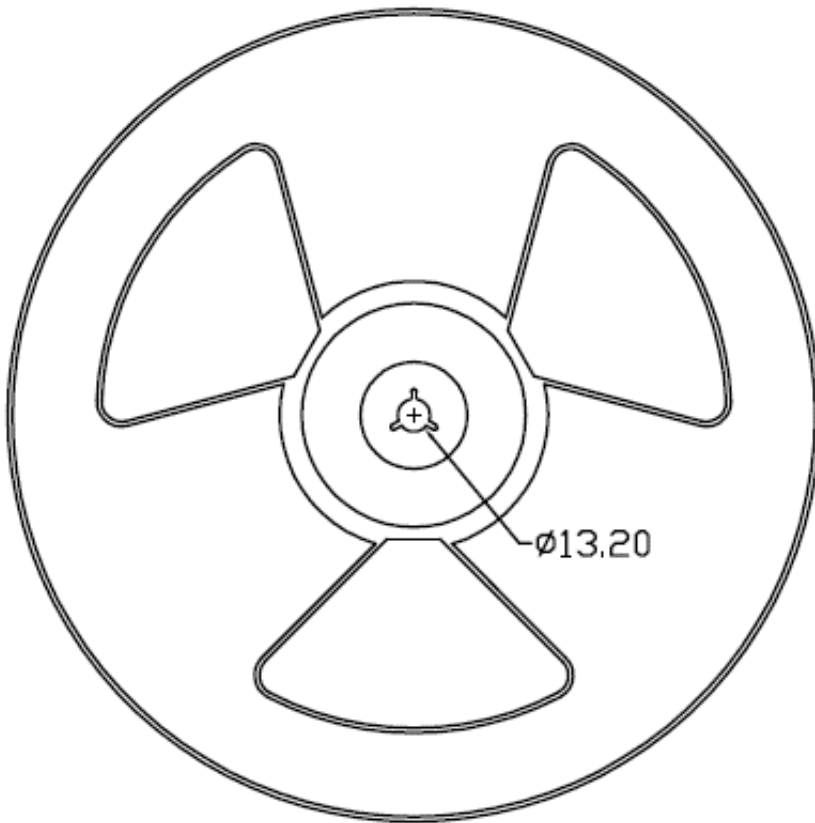
Option T2





REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

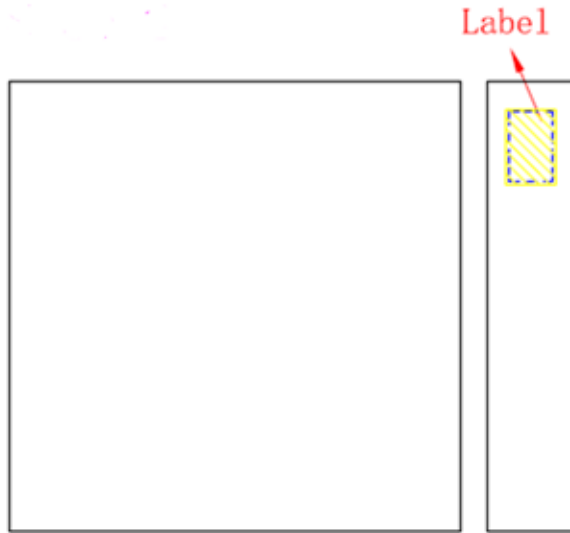
Option T1 & T2





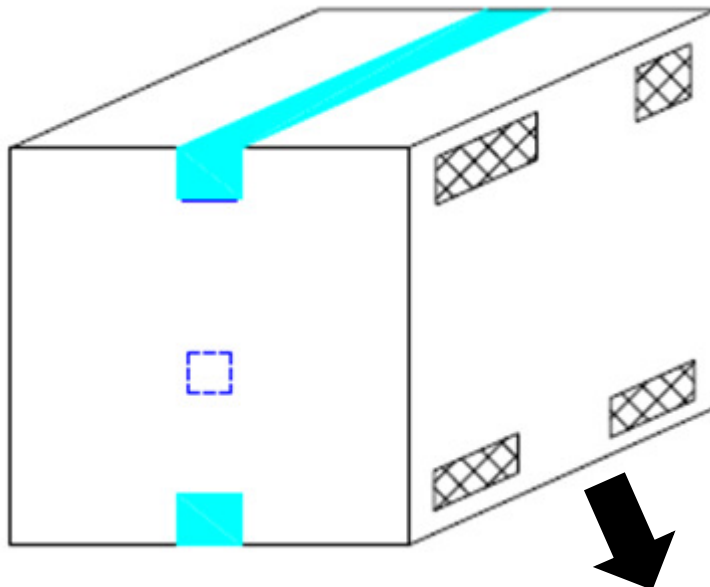
BOX SPECIFICATIONS (Reel Type)

Inner Box



- L x W x H = 36cm x 36cm x 6.9cm

Outer Box



- L x W x H = 45cm x 38cm x 38cm





ORDERING AND MARKING INFORMATION

MARKING INFORMATION



BF : Company Abbr.
101X : Part Number& Rank
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

BF101X(Z)-GV

BF – Company Abbr.
 101X – Rank (0/1/2/3/4/5/6/7/8/9)
 T – Tape and Reel Option (T1/T2)
 G – Green
 V – VDE Option (V or None)

LABEL INFORMATION

毕方半导体（深圳）有限公司
 BF Semiconductor(ShenZhen) Co., Ltd
 Part No : XXXXXXXXXXXXX Bin Code : X
 Lot No : XXXXXXXXXXXX
 Date Code : XXXX
 Q'ty : XXXX pcs

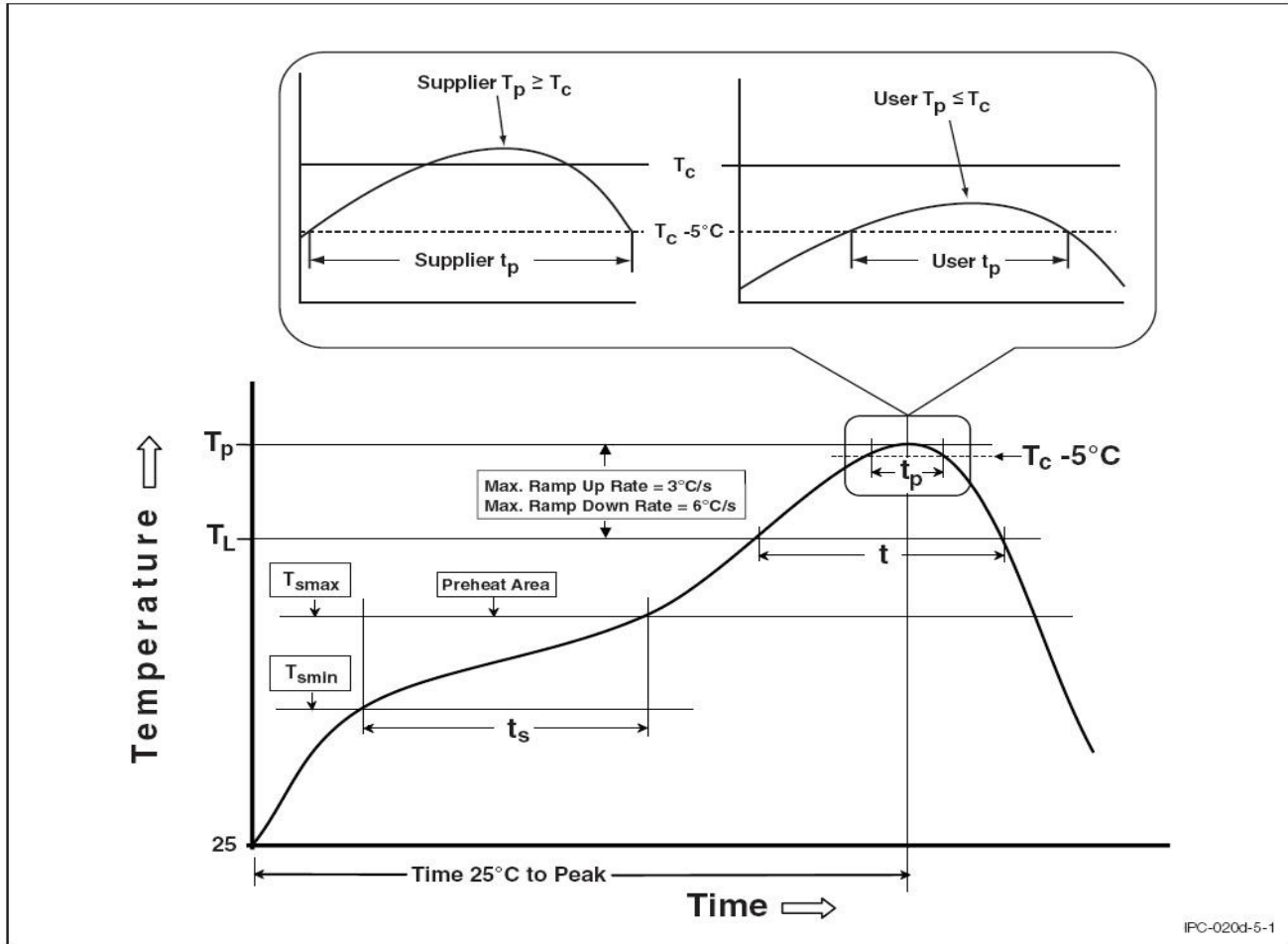
PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units
T2	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units



TEMPERATURE PROFILE OF SOLDERING

IR REFLOW SOLDERING (J-STD-020D COMPLIANT)



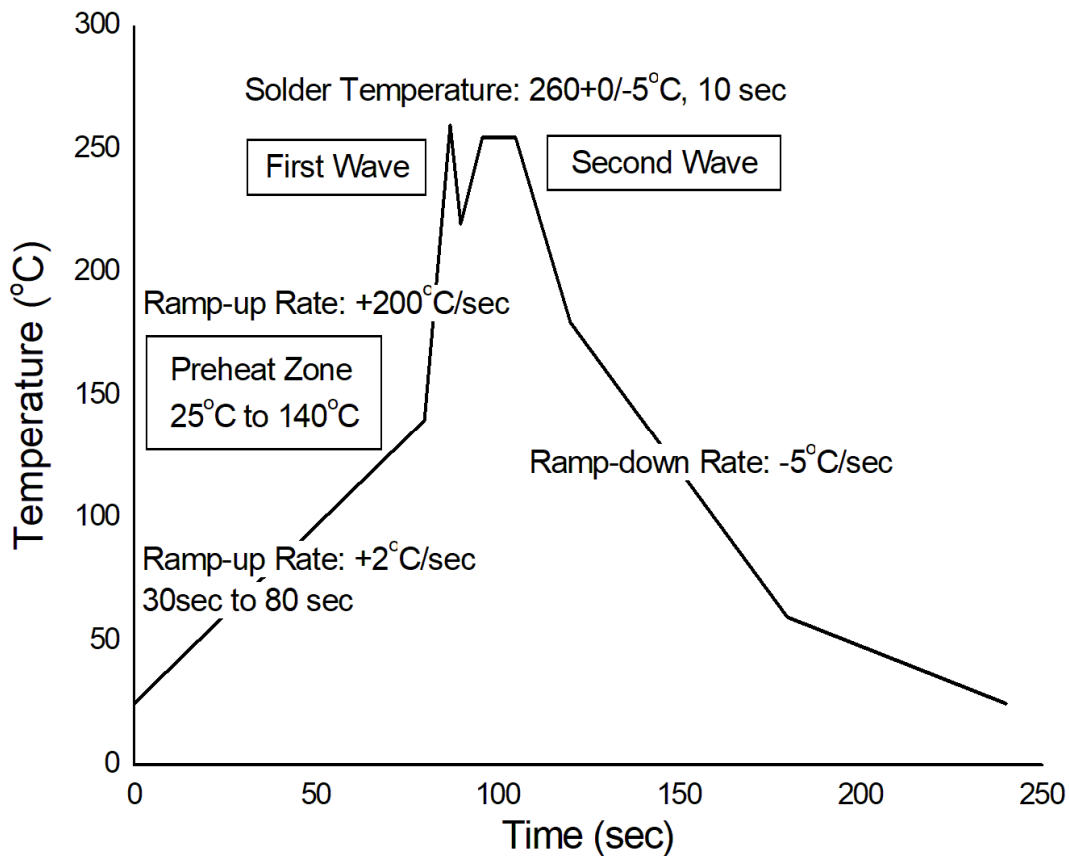
IPC-020d-5-1

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	100	150°C
Temperature Max. (Tsmmax)	150	200°C
Time (ts) from (Tsmmin to Tsmmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



TEMPERATURE PROFILE OF SOLDERING

WAVE SOLDERING (JESD22-A111 COMPLIANT)



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

Note 5. One time soldering is recommended for all soldering method.

Note 6. Do not solder more than three times for IR reflow soldering.



DISCLAIMER

- BF SEMICONDUCTOR is continually improving the quality, reliability, function and design. BF SEMICONDUCTOR reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performances which are not guaranteed.
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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact BF SEMICONDUCTOR sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify BF SEMICONDUCTOR's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.